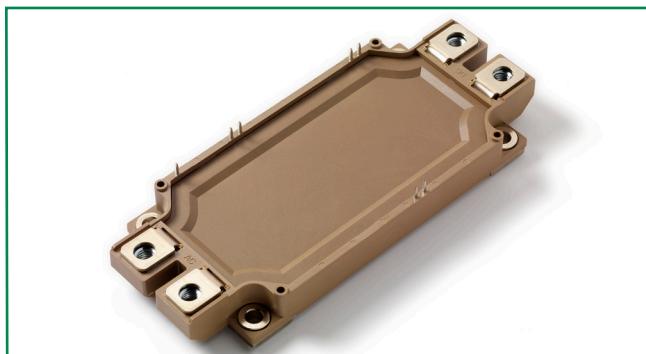


MG12600WB-BR2MM



Features

- Trench-gate field stop IGBT technology
- Free wheeling diodes with fast and soft reverse recovery
- Low saturation voltage and positive temperature coefficient
- Temperature sense included
- Fast switching and short tail current
- $T_{J\max} = 175^\circ\text{C}$

Applications

- Industrial and servo drives
- UPS
- Welding
- Solar inverters
- RoHS compliant
- High-power converters

Agency Approvals

AGENCY	AGENCY FILE NUMBER
	E71639

Module Characteristics ($T_c = 25^\circ\text{C}$, unless otherwise specified)

Symbol	Parameters	Test Conditions	Values	Unit
$T_{J\max}$	Max. Junction Temperature		175	$^\circ\text{C}$
T_{Jop}	Operating Temperature		-40~150	$^\circ\text{C}$
T_{stg}	Storage Temperature		-40~125	$^\circ\text{C}$
V_{isol}	Isolation Breakdown Voltage to heatsink Torque lolerminal	AC, 50 Hz(R.M.S), t = 1 minute	3000	V
		Recommended (M5)	2.5~5	N·m
		Recommended (M6)	3~5	N·m
Weight			350	g

Absolute Maximum Ratings ($T_c = 25^\circ\text{C}$, unless otherwise specified)

Symbol	Parameters	Test Conditions	Values	Unit
IGBT				
V_{CES}	Collector Emitter Voltage	$T_j = 25^\circ\text{C}$	1200	V
V_{GES}	Gate Emitter Voltage		± 20	V
I_c	DC Collector Current	$T_c = 25^\circ\text{C}$	750	A
		$T_c = 80^\circ\text{C}$	600	A
I_{CM}	Repetitive Peak Collector Current	$t_p = 1\text{ ms}$	1200	A
P_{tot}	Power Dissipation Per IGBT		2500	W
Diode				
V_{RRM}	Repetitive Reverse Voltage	$T_j = 25^\circ\text{C}$	1200	V
$I_{F(AV)}$	Average Forward Current	$T_c = 25^\circ\text{C}$	600	A
I_{FRM}	Repetitive Peak Forward Current	$t_p = 1\text{ ms}$	1200	A
I^2t		$T_j = 125^\circ\text{C}, t = 10\text{ ms}, V_R = 0\text{ V}$	45	KA ² s

1200 V 600 A IGBT Module

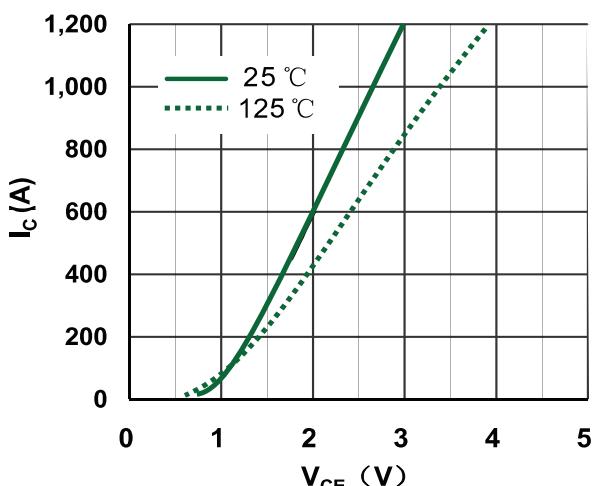
Electrical and Thermal Specifications ($T_c = 25^\circ\text{C}$, unless otherwise specified)

Symbol	Parameters		Test Conditions	Min	Typ	Max	Unit		
IGBT									
$V_{GE(\text{th})}$	Gate Emitter Threshold Voltage		$V_{CE} = V_{GE}, I_c = 24 \text{ mA}$	5.0	5.4	6.4	V		
$V_{CE(\text{sat})}$	Collector Emitter Saturation Voltage	chip	$I_c = 600 \text{ A}, V_{GE} = 15 \text{ V}, T_j = 25^\circ\text{C}$		1.7	2.15	V		
			$I_c = 600 \text{ A}, V_{GE} = 15 \text{ V}, T_j = 125^\circ\text{C}$		1.9				
	Collector Emitter Saturation Voltage	terminal	$I_c = 600 \text{ A}, V_{GE} = 15 \text{ V}, T_j = 25^\circ\text{C}$		2.0	2.5	V		
			$I_c = 600 \text{ A}, V_{GE} = 15 \text{ V}, T_j = 125^\circ\text{C}$		2.4				
I_{CES}	Collector Leakage Current		$V_{CE} = 1200 \text{ V}, V_{GE} = 0 \text{ V}, T_j = 25^\circ\text{C}$		100		μA		
			$V_{CE} = 1200 \text{ V}, V_{GE} = 0 \text{ V}, T_j = 125^\circ\text{C}$		1		mA		
I_{GES}	Gate Leakage Current		$V_{CE} = 0 \text{ V}, V_{GE} = \pm 15 \text{ V}, T_j = 125^\circ\text{C}$	-400		400	nA		
R_{Gint}	Integrated Gate Resistor				0.5		Ω		
Q_g	Gate Charge		$V_{CE} = 600 \text{ V}, I_c = 600 \text{ A}, V_{GE} = \pm 15 \text{ V}$		3.4		μC		
C_{ies}	Input Capacitance		$V_{CE} = 25 \text{ V}, V_{GE} = 0 \text{ V}, f = 1 \text{ MHz}$		60.5		nF		
C_{res}	Reverse Transfer Capacitance				1.8		nF		
$t_{d(on)}$	Turn-on Delay Time		$V_{CC} = 600 \text{ V}$ $I_c = 600 \text{ A}$ $R_G = 5 \Omega$ $V_{GE} = \pm 15 \text{ V}$ Inductive Load	$T_j = 25^\circ\text{C}$	250		ns		
t_r	Rise Time			$T_j = 125^\circ\text{C}$	280		ns		
$t_{d(off)}$	Turn-off Delay Time			$T_j = 25^\circ\text{C}$	220		ns		
t_f	Fall Time			$T_j = 125^\circ\text{C}$	240		ns		
E_{on}	Turn-on Energy			$T_j = 25^\circ\text{C}$	1000		ns		
E_{off}	Turn-off Energy			$T_j = 125^\circ\text{C}$	1100		ns		
I_{SC}	Short Circuit Current			$T_j = 25^\circ\text{C}$	170		ns		
E_{rec}				$T_j = 125^\circ\text{C}$	190		ns		
E_{rec}				$T_j = 25^\circ\text{C}$	20		mJ		
E_{rec}				$T_j = 125^\circ\text{C}$	35		mJ		
I_{SC}				$T_j = 25^\circ\text{C}$	105		mJ		
E_{rec}				$T_j = 125^\circ\text{C}$	120		mJ		
R_{thJC}	Junction-to-Case Thermal Resistance (Per IGBT)				2400		A		
Diode									
V_F	Forward Voltage	chip	$I_F = 600 \text{ A}, V_{GE} = 0 \text{ V}, T_j = 25^\circ\text{C}$		2.1	2.5	V		
			$I_F = 600 \text{ A}, V_{GE} = 0 \text{ V}, T_j = 125^\circ\text{C}$		2.2		V		
t_{RR}	Reverse Recovery Time		$I_F = 600 \text{ A}, V_R = 600 \text{ V}$ $dI/dt = -2700 \text{ A}/\mu\text{s}$ $T_j = 125^\circ\text{C}$		330		ns		
I_{RRM}	Max. Reverse Recovery Current				305		A		
Q_{RR}	Reverse Recovery Charge				96		μC		
E_{rec}	Reverse Recovery Energy				42		mJ		
R_{thJCD}	Junction-to-Case Thermal Resistance (Per Diode)					0.1	K/W		

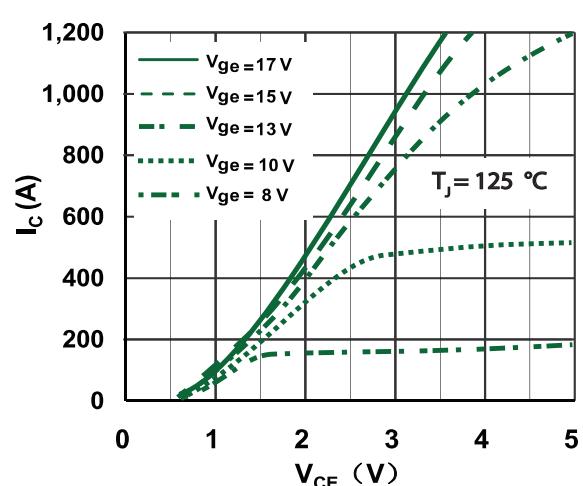
NTC Characteristics ($T_c = 25^\circ\text{C}$, unless otherwise specified)

Symbol	Parameters		Test Conditions	Min	Typ	Max	Unit
R_{25}	Resistance		$T_c = 25^\circ\text{C}$		5		$\text{k}\Omega$
$B_{25/50}$	$R_2 = R_{25} \exp [B_{25/50} (1/T_2 - 1/(298, 15 \text{ K}))]$			3375			K

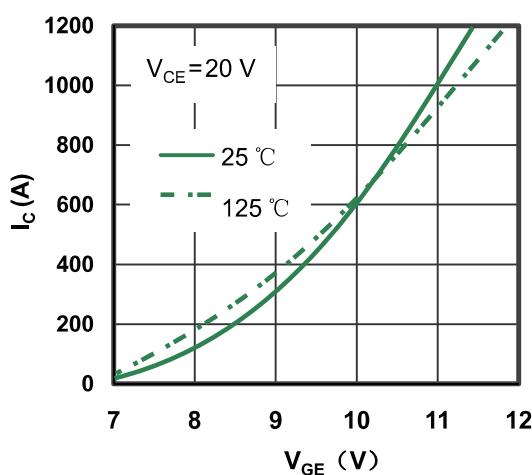
**Figure 1: Typical Output Characteristics
IGBT Inverter**



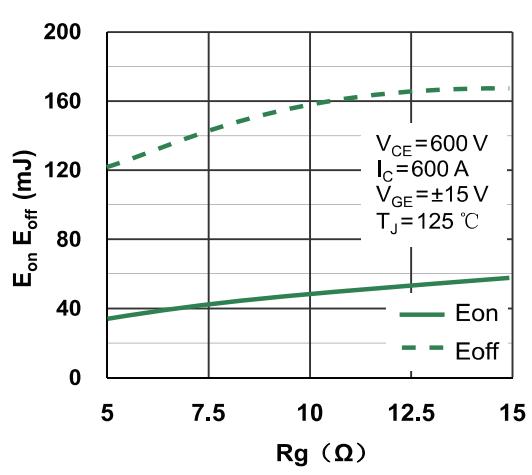
**Figure 2: Typical Output Characteristics
IGBT Inverter**



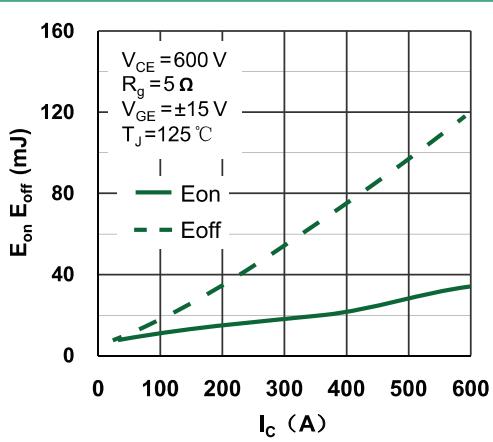
**Figure 3: Typical Transfer Characteristics
IGBT Inverter**



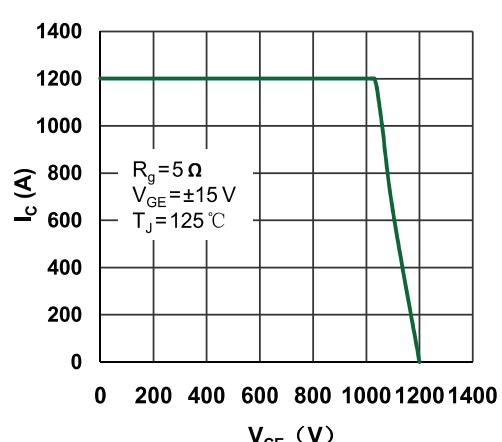
**Figure 4: Switching Energy vs. Gate Resistor
IGBT Inverter**



**Figure 5: Switching Energy vs. Collector Current
IGBT Inverter**



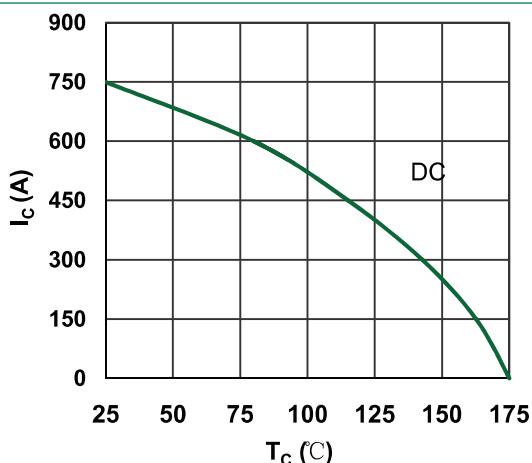
**Figure 6: Reverse Biased Safe Operating Area
IGBT Inverter**



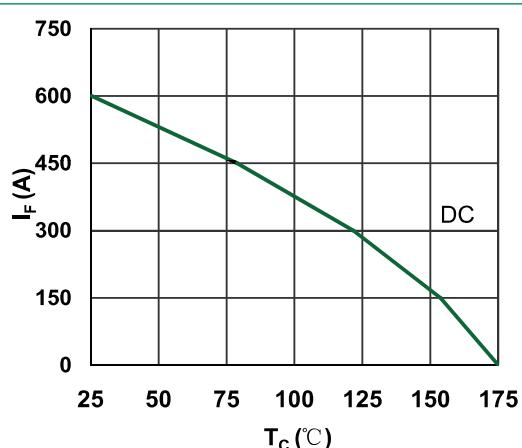
IGBT Power Module

1200 V 600 A IGBT Module

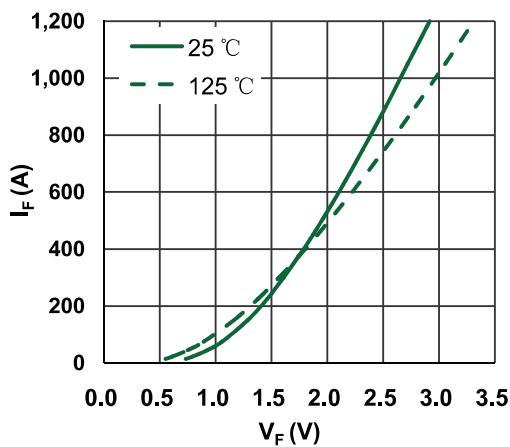
**Figure 7: Collector Current vs Case temperature
IGBT -inverter**



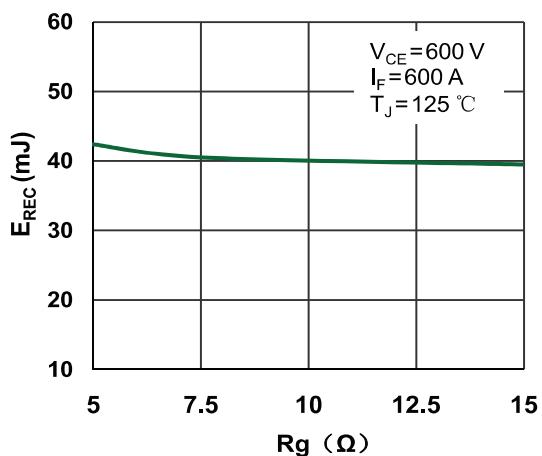
**Figure 8: Forward current vs Case temperature
Diode -inverter**



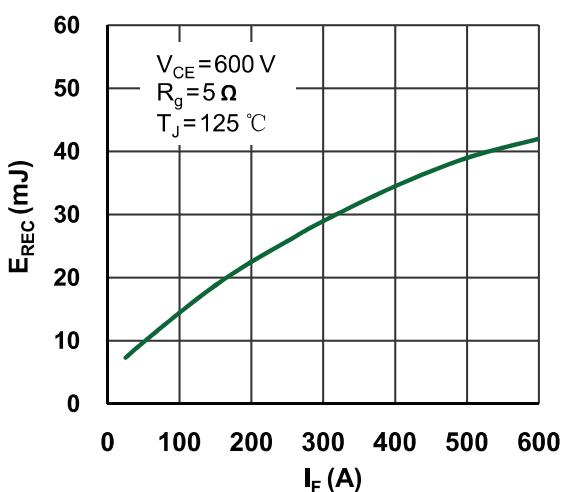
**Figure 9: Diode Forward Characteristics
Diode -inverter**



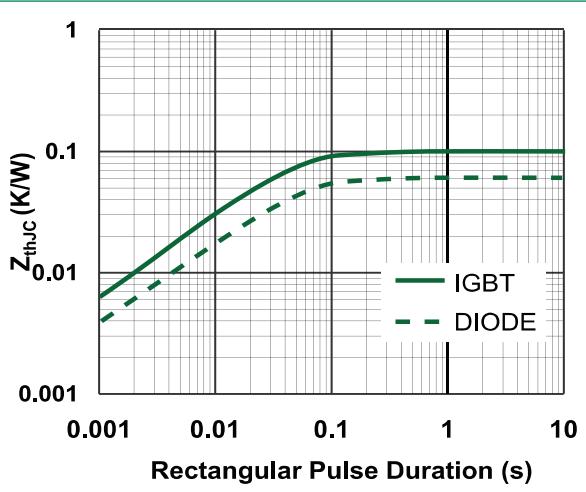
**Figure 10: Switching Energy vs Gate Resistor
Diode -inverter**



**Figure 11: Switching Energy vs Forward Current
Diode-inverter**

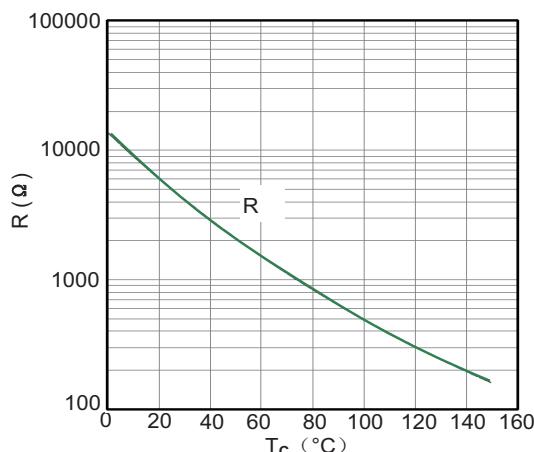


**Figure 12: Transient Thermal Impedance of
Diode and IGBT -inverter**

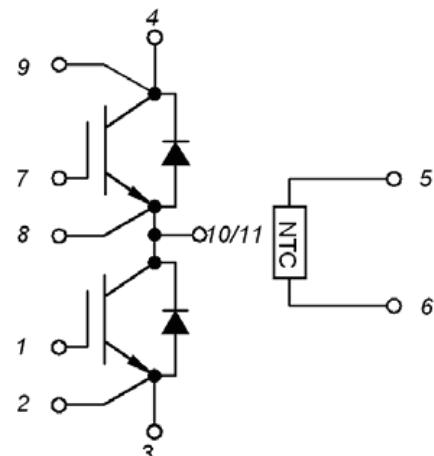


1200 V 600 A IGBT Module

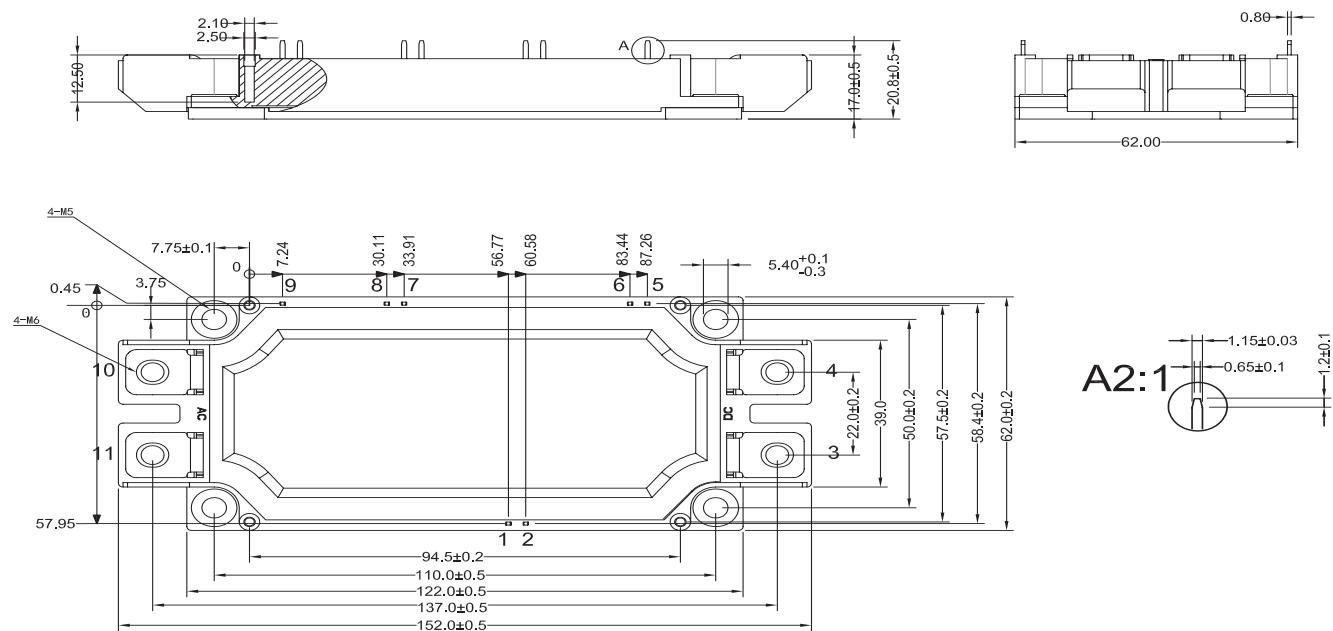
Figure 13: NTC Characteristics



Circuit Diagram



Dimensions-Package WB



The foot pins are in gold / nickel coating

Packing Options

Part Number	Marking	Weight	Packing Mode	M.O.Q
MG12600WB-BR2MM	MG12600WB-BR2MM	350 g	Bulk Pack	60

Part Numbering System

MG12600 WB - B R2 MM

PRODUCT TYPE
M: Power Module

MODULE TYPE
G: IGBT

VOLTAGE RATING
12: 1200 V

CURRENT RATING
600: 600 A

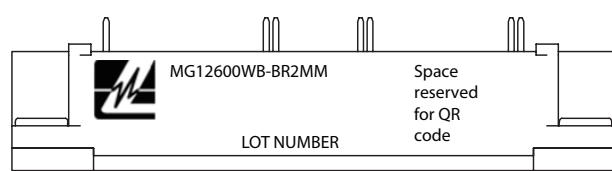
ASSEMBLY SITE

WAFER TYPE

CIRCUIT TYPE
2x(IGBT+FWD)

PACKAGE TYPE

Part Marking System



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[FD401R17KF6C_B2](#) [FD-DF80R12W1H3_B52](#) [FF200R06YE3](#) [FF300R12KE4_E](#) [FF450R12ME4P](#) [FF600R12IP4V](#) [FP10R06W1E3_B11](#)
[FP20R06W1E3](#) [FP50R12KT3](#) [FP75R07N2E4_B11](#) [FS10R12YE3](#) [FS150R07PE4](#) [FS150R12PT4](#) [FS200R12KT4R](#) [FS50R07N2E4_B11](#)
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[DF400R07PE4R_B6](#) [BSM75GB120DN2_E3223c-Se](#) [F3L300R12ME4_B22](#) [F3L75R07W2E3_B11](#) [F4-50R12KS4_B11](#)
[F475R07W1H3B11ABOMA1](#) [FD1400R12IP4D](#) [FD200R12PT4_B6](#) [FD800R33KF2C-K](#) [FF1200R17KP4_B2](#) [FF300R17KE3_S4](#)
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[FS100R07PE4](#) [FS150R07N3E4_B11](#) [FS150R17N3E4](#) [FS150R17PE4](#)